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SCCE Manual Digital Library Prior Format	[Abstract] [PDF Full-Text (2	24 KB)] IEEE CNF	

Collins, L.;

IEE Review, Volume: 49 Issue: 2, Feb. 2003

Page(s): 42 -45

[Abstract] [PDF Full-Text (340 KB)] **IEE JNL**

3 An organic thin film transistor backplane for flexible liquid crystal displays

Sheraw, C.D.; Nichols, J.A.; Gundlach, D.J.; Huang, J.R.; Kuo, C.C.; Klauk, H.; Jackson, T.N.; Kane, M.G.; Campi, J.; Cuomo, F.P.; Greening, B.K.;

Device Research Conference, 2000. Conference Digest. 58th DRC , 19-21 June 2000

Page(s): 107 -108

[Abstract] [PDF Full-Text (180 KB)] IEEE CNF

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2 Smart-cards-a cost-effective solution against electronic fraud

Lassus, M.

Security and Detection, 1997. ECOS 97., European Conference on , 1997

Page(s): 81 -85

[Abstract] [PDF Full-Text (340 KB)] CNF

3 Paper based document security-a review

van Renesse, R.L.

Security and Detection, 1997. ECOS 97., European Conference on , 1997

Page(s): 75 -80

[Abstract] [PDF Full-Text (508 KB)] CNF

4 Crypt graphic smart cards

Naccache, D.; M'Raihi, D.

IEEE Micro , Volume: 16 Issue: 3 , June 1996

Page(s): 14, 16 -24

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A Print Format	[Abstract] [PDF Full-Text (3	28 KB)] CNF

77 A new concept for medium-voltage cables: improved voltage life of belt-type cables

Kreuger, F.H.; Morshuis, P.H.F.; van de Laar, A.M.F.

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation, IEEE Transactions on], Volume: 24 Issue: 6,

Dec. 1989

Page(s): 1063 -1070

[Abstract] [PDF Full-Text (468 KB)] JNL

78 Dielectric breakdown strength affected by the lamellar configuration in XLPE insulation at a semiconducting interface

Okamoto, T.; Ishida, M.; Hozumi, N.

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation, IEEE Transactions on], Volume: 24 Issue: 4,

Aug. 1989

Page(s): 599 -607

[Abstract] [PDF Full-Text (644 KB)] JNL

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[Abstract] [PDF Full-Text (393 KB)] CNF

2 Will polymer electronics change the electronics industry? *Hofstraat, H.*

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

Page(s): 1 -8

[Abstract] [PDF Full-Text (713 KB)] CNF

3 Manufacturability and reliability of non-halogenated molding compounds

Cada, L.G.; Lalanto, R.; Coronel, G.; San Gregorio, N.; Asis, D.; Ong, G.; Ducusin, C.; Desengano, R.; Llamas, T.; Decena, R.; Canares, N.; Reyes, A.; Miciano, P.

Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceedings of 3rd , 2000

Page(s): 15 -20

[Abstract] [PDF Full-Text (324 KB)] CNF

4 P lymer pt electr nics and semiconductor grafting for aer space applications

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2 Will polymer electronics change the electronics industry? *Hofstraat, H.*

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001 $\,$

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0		2003/07/15 12:46	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer)	134	BRS	122
0		2003/07/15 10:09	USPAT; US-PGPUB	flexibility (integrated chip semico	9506	BRS	121
0		2003/07/15	EPO; JPO; DERWENT; IBM_TDB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20021031	32	120 BRS	120
0		, 2003/07/15 09:49	USPAT; US-PGPUB	((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1)) same (IC chip circuit semiconductor semiconducting)) not ((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting)) and @pd>20021031	3	BRS	119
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0			2003/07/15		EPO; JPO; DERWENT; IBM_TDB	near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer)	71	125 BRS	125
0			2003/07/15	· •	EPO; JPO; DERWENT; IBM_TDB	flexibility bend\$4) (integrated adj) chip semiconductor) ganic carbon) near5	5	124 BRS	124
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